

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
4 May 2006 (04.05.2006)

PCT

(10) International Publication Number
WO 2006/045995 A1

- (51) International Patent Classification⁷: **C22C 13/00**, B23K 35/26
- (21) International Application Number: PCT/GB2005/003338
- (22) International Filing Date: 26 August 2005 (26.08.2005)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
0423860.6 27 October 2004 (27.10.2004) GB
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- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- with amended claims

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: IMPROVEMENTS IN OR RELATING TO SOLDERS

(57) Abstract: A lead-free solder, comprising: from around 96.8% to around 99.3% tin; from 0.2% to 3.0% copper; from 0.02% to around 0.12% silicon, and optionally 0.005% to 0.01% P and/or 0.0005%-0.01 Ge.

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